

**Journal of Materials Research**  
**Articles in the August 1990 Issue (Vol. 5 No. 8)**

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Characterization of Spray-Pyrolized Superconducting YBa-CuO Thin Films on Single-Crystal MgO by Transmission Electron Microscopy, by S.J. Golden, H. Isotalo, M. Lanham, J. Mayer, F.F. Lange, and M. Rühle.

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